

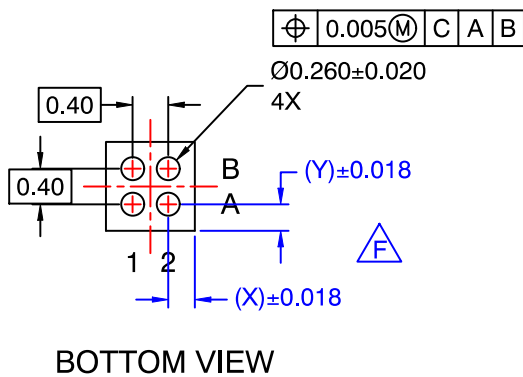
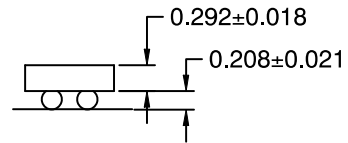
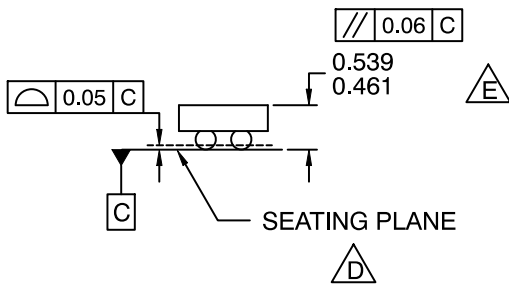
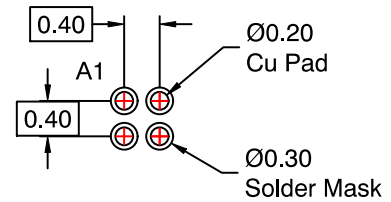
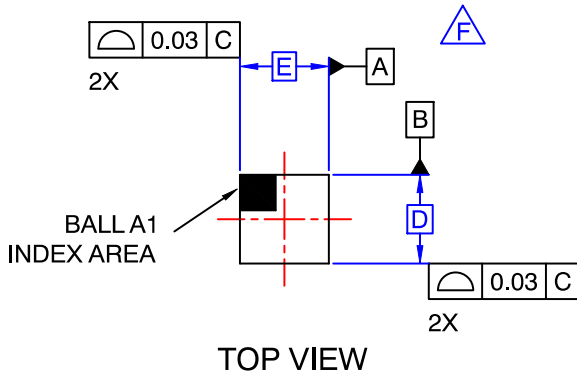
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP4 0.76x0.76x0.586
CASE 567SS
ISSUE O

DATE 30 NOV 2016



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- D** DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E** PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461–539 MICRONS).
- F** FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP4 0.76x0.76x0.586	PAGE 1 OF 1

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